Chip Scale Review

2019 Editorial Calendar

(Editorial close date: 12/1/2018 **January • February** Industry Events *** indicates show distribution**

Topics	Industry Events
New test methodologies for 5G	• **APEX Expo** San Diego, CA (Jan 26-31)
RF/OTA	• **3D & Systems Summit** Dresden, Germany (Jan 28-30)
Thermal debonding and warpage in FOWLP	• **SMTA Pan Pac Microelectronics Symposium** Kauai, Hawaii (Feb 11-14)
W2W/D2W & other bonding advances for 3D ICs	• **FLEX / MEMS & Sensors Technical Congress** Monterey, CA (Feb 18-21)
Temporary bonding & the challenges of cleaning post debond	
Discontinuities drive data integration	
IC packaging for Moore's Law	
Heterogeneous integration	
Thin wafer handling	

Ad Space Close Jan 18 - Ad Materials Close Jan 25

(Editorial close date: 2/28/19) **March • April** Industry Events *** indicates show distribution**

Topics	Industry Events
Power devices	• **TestConX** Mesa, AZ (March 3-6)
Packaging of implantable devices	• **IMAPS Device Packaging** Fountain Hills, AZ (March 4-7)
Silicone surface contamination for optimizing package assembly	• **SEMI-THERM** San Jose, CA (March 18-22)
Electroplating models for 3D TSVs	• **SEMICON China** Shanghai, China (March 20-22)
Failure relief in WLP & PLP polymer layers	• **ISS Europe** Milan, Italy (March 31-April 2**)**
Automotive IC production wafer test in a zero-defect world	
Testing of HF 5G applications and why simulations are critical to success	
High-density and high-bandwidth C2C connections	

Ad Space Close Mar 15 - Materials Close Mar 22

(Editorial close date: 4/1) **May • June** Industry Events *** indicates show distribution**

Topics	Industry Events
Automotive packaging	• **SEMICON SE Asia** Kuala Lumpur, Malaysia (May 7-9)
Market drivers in automotive	• **Meptec/SMTA Medical Electronics Symposium** Elyria, OH (May 20-21)
Dispensed materials for additive manufacturing	• **ECTC** Las Vegas, NV (May 28-31)
Wafer scribing/dicing	• **IEEE/SW Test Workshop (SWTW)** San Diego, CA (June 2-5)
Customization of electroplating chemistries	• **Sensors Expo** San Jose, CA (June 25-27)
Inspection and metrology challenges	• **SEMICON West** San Francisco, CA (July 9-11)
Multi-functional adhesives	
Stretchable interconnects	
Bonding dielectrics for heterogeneous integration	
Smart devices and applications	

International Directory of Wafer Dicing & Scribing Systems ***Ad Space Close May 10 - Ad Materials Close May 17***

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